Hybrid 7z179 Traveler

February 3, 2000

1 Connectivity

Repairs on shorts:

Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 7Z179 has die: 226-003 226-004 226-007 226-008 226-009 226-012 226-014

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 7z179 classification info. Created 09:23:33 01/31/00

Hybrid 7z179 quality: fair
Chip classification: good fair good fair fair good good
Bad channels (chip-channel): 1-69 3-101
Bad cells: none
Random bad capacitors (chip-cell-channel): 4-11-3 4-12-3 4-14-2
   4-14-3 4-16-2 4-16-3 4-18-2 4-18-3 4-27-2 4-27-3 4-28-3
   4-8-3
Channels at pedestal needed for DCMS: 31.7 29.8 33.7 30.7 34.6 32.7 31.7
```

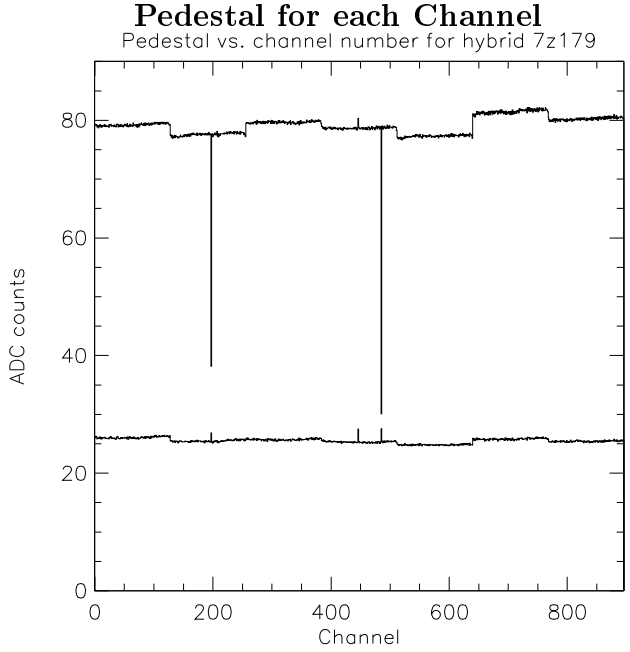
4 Comments

Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

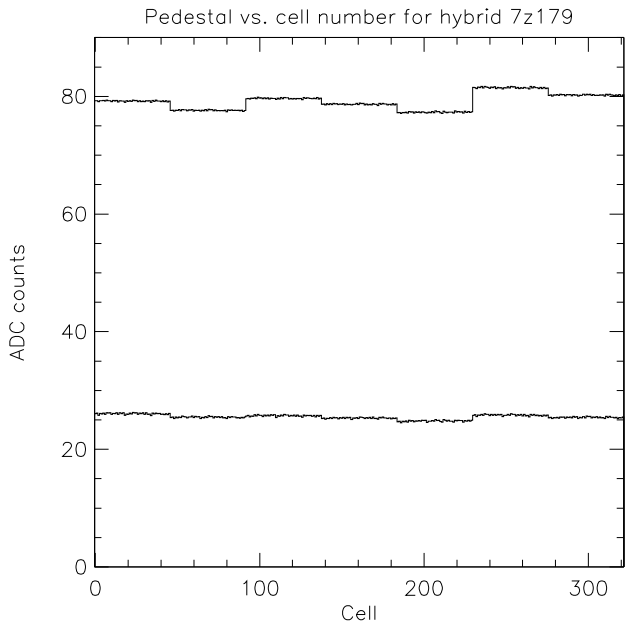
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

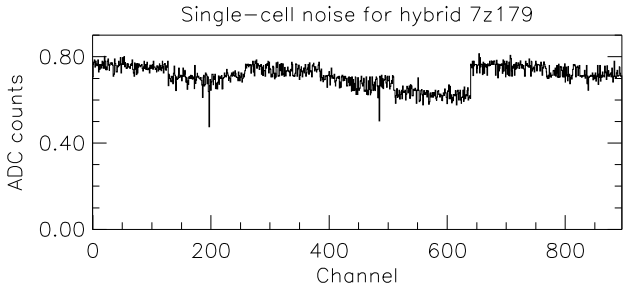
Pedestal vs. Pipeline Cell ID

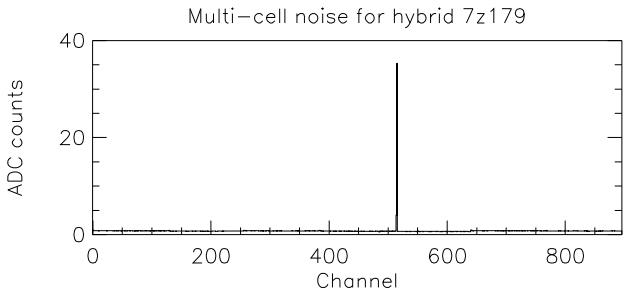


6 Noise

The following plots show the single-cell and multi-cell RMS noise:

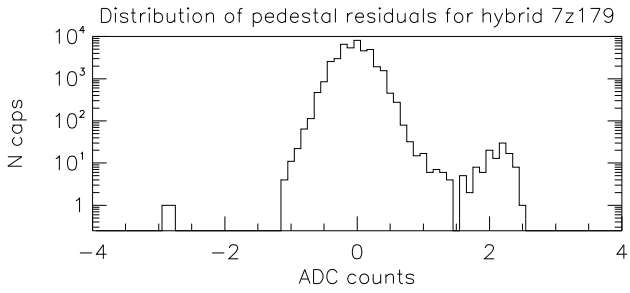
RMS Noise

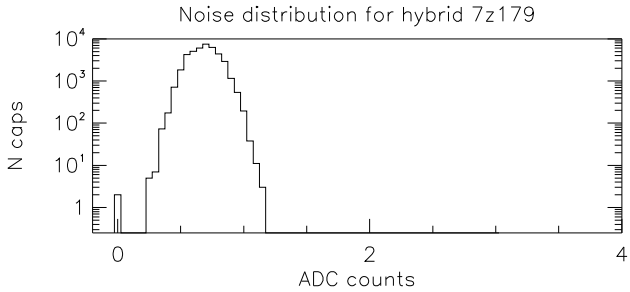




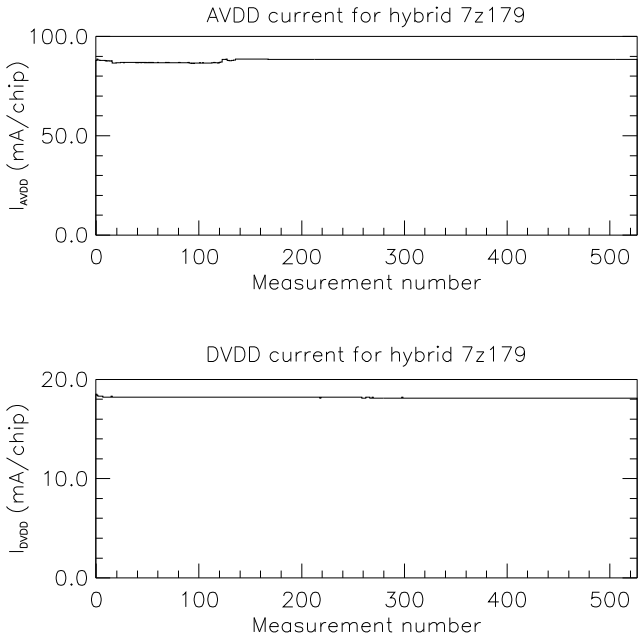
The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise





7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in